Materials Declaration

Package	LFCSP
Body Size	8 X 8 X 0.85
LeadCount	56
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	85	5.57 E-02	328236
Epoxy Resin	10	6.55 E-03	38616
Phenol Resin	5	3.27 E-03	19308
Subtotal		6.55 E-02	386160

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	8.81 E-02	519307
Fe	2.35	2.12 E-03	12517
Zn	0.12	1.08 E-04	639
P	0.03	2.71 E-05	160
Subtotal		9.03 E-02	532622

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.85 E-03	10933

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.90 E-04	2297

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.02 E-03	6012

Chip

	% of Chip	Weight (g)	PPM
Si	100	9.02 E-03	53210

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	1.12 E-03	6575
Resin	25	3.72 E-04	2192
Subtotal		1.49 E-03	8766

Package Totals

Weight (g)	PPM
1.70 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	3	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

ADI Proprietary

Materials Declaration

Package	LFCSP
Body Size	8 X 8 X 0.85
LeadCount	56
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	85	5.57 E-02	328236
Epoxy Resin	10	6.55 E-03	38616
Phenol Resin	5	3.27 E-03	19308
Subtotal		6.55 E-02	386160

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	8.81 E-02	519307
Fe	2.35	2.12 E-03	12517
Zn	0.12	1.08 E-04	639
P	0.03	2.71 E-05	160
Subtotal		9.03 E-02	532622

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.85 E-03	10933

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	3.31 E-04	1952
Pb	15	5.84 E-05	345
Subtotal		3.90 E-04	2297

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.02 E-03	6012

Chip

	% of Chip	Weight (g)	PPM
Si	100	9.02 E-03	53210

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	1.12 E-03	6575
Resin	25	3.72 E-04	2192
Subtotal		1.49 E-03	8766

Package Totals

Weight (g)	PPM
1.70 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	3	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

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